

ABSTRACT OF THE DISCLOSURE

A chip package structure comprising a carrier, a chip, a plurality of passive components, a plurality of conductive wires and some insulating material is provided. The passive components are attached to the surface of the carrier with its electrodes
5 connected to a power contact and a ground contact respectively. The conductive wires cross over the passive components with its ends connected respectively to a bonding pad on the chip and a signal contact close to the edge of the carrier. With the wires crossing over the passive components that are positioned close to a chip bonding area of the carrier, contact between the wires and the electrodes is prevented and the space for
10 accommodating conductive wires is increased.